Loctite® 3564 Fast flow epoxy, moderate CTE and Tg Fast Flow Underfill

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy Encapsulant, Unreinforced

Material Notes:

COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate.Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds.Loctite® 3564 Fast flow epoxy, moderate CTE and Tg Fast Flow UnderfillAn extremely fast flowing, rapid cure underfill for industrial and consumer flip chip applications. Withstands operating temperatures up to 125°C.

Order this product through the following link: http://www.lookpolymers.com/polymer_Loctite-3564-Fast-flow-epoxy-moderate-CTE-and-TgFast-Flow-Underfill.php

Physical Properties	Metric	English	Comments
Density	1.50 g/cc	0.0542 lb/in ³	
Viscosity	3000 cP	3000 cP	Haake cone and plate rheometer @ 5/sec (35mm/2° cone)

Mechanical Properties	Metric	English	Comments
Tensile Modulus	3.10 GPa	450 ksi	

Thermal Properties	Metric	English	Comments
CTE, linear	35.0 μm/m-°C	19.4 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Glass Transition Temp, Tg	125 °C	257 °F	

Processing Properties	Metric	English	Comments
Cure Time	20.0 min	0.333 hour	
	@Temperature 150 °C	@Temperature 302 °F	
Shelf Life	3.00 Month	3.00 Month	
	@Temperature -40.0 °C	@Temperature -40.0 °F	

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